

# Final Product/Process Change Notification Document #: FPCN22453X

Issue Date: 16 October 2018

Title of Change:	Wafer fab site transfer of HDG4 technology products from ON Semiconductor Bucheon, Korea to ON Semiconductor South Portland, Maine (Main Fab).				
Proposed first ship date:	23 Januar	ry 2019			
Contact information:	Contact y	our local ON Semiconductor Sales	Office o	r < <u>Sungdae.Shin@onsemi.com</u> >.	
Samples:	Contact your local ON Semiconductor Sales Office or < <a href="mailto:PCN.samples@onsemi.com">PCN.samples@onsemi.com</a> Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change.				PCN or
Additional Reliability Data:	Contact y	our local ON Semiconductor Sales	Office o	r < <u>Byeongyeop.Lee@onsemi.com</u> >	
Type of notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change.  ON Semiconductor will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact < < PCN. Support@onsemi.com >				
Change Part Identification:	Affected products will be identified with date code.				
Change Category:	▼ Wafer Fab Change				
Change Sub-Category(s):  ☐ Manufacturing Site Addition ☐ Manufacturing Site Transfer ☐ Manufacturing Process Change ☐ Datasheet/Product Doc change ☐ Shipping/Packaging/Marking ☐ Other:					
Sites Affected:	ON Semiconductor Sites: ON Suzhou, China ON Bucheon, Korea ON S. Portland, Maine  External Foundry/Subcon Sites: None				
Description and Purpose:					
This Final notification announces to customers the transfer of waferfab site for HDG4 technology products from ON Semiconductor Bucheon, Korea to ON Semiconductor South Portland, Maine (Main Fab).					
		Before Change Description	- 1	After Change Description	
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Wafer Fab	change	ON Semiconductor Bucheon, Korea	ON Se	emiconductor South Portland, Maine ( Main Fab)	

TEM001793 Rev. A Page 1 of 2



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### Reliability Data Summary:

**QV DEVICE NAME:** FAN7380MX

RMS: **Q20150205** PACKAGE: 8SOIC

Test	Specification	Condition	Interval	Results
HTRB	JESD22-A108	Ta=125°C, HS=500V	1,008 hrs	0/231
HTOL	JESD22-A108	Ta=125°C, Vcc=20V	1,008 hrs	0/231
GL+	AEC-Q100-006	Ta=155°C, +400V		0/9
GL-	AEC-Q100-006	Ta=155°C, -400V		0/9
HTSL	JESD22-A103	Ta=150°C	1,008 hrs	0/231
TC	JESD22-A104	Ta= -65°C to +150°C	500 cyc	0/231
HAST	JESD22-A110	110°C, 85% RH, 18.8psig, Vcc=10V	264 hrs	0/135
PC	J-STD-020 JESD-A113	MSL 1 @ 260 °C		0/366
CDM	JESD22-C101	2.0kV, Determine LPV		0/9
НВМ	JESD22-A114	0.7kV, Determine LPV		0/9
LU	JESD 78	Determine LPI		0/9
BPULL	JESD22-C100			0/15
BSHR	AEC-Q100-001			0/15
DSHR	MIL-STD-883-2019			0/15
Bond Cratering		Post Bond Metal Etch Crater Test		0/15

QV DEVICE NAME : FSSP50CH60S

RMS: **Q20150205** PACKAGE: <u>SPIM</u>

Test	Specification	Condition	Interval	Results
TC	JESD22-A104	Ta= -40°C to +125°C	200 cyc	0/77

#### Electrical Characteristic Summary:

Electrical characteristics are not impacted.

#### **List of Affected Parts:**

Part Number	Qualification Vehicle	
FSB50250		
FSB50250US		
FSB50450	FAN7380MX FSSP50CH60S	
FSB50450US	135. 33611003	
FSB50825US		

TEM001793 Rev. A Page 2 of 2



## **Appendix A: Changed Products**

Product	Customer Part Number	Qualification Vehicle
FSB50250		FSSP50CH60S/FSB50450S
FSB50250US		FSSP50CH60S/FSB50450S
FSB50450		FSSP50CH60S/FSB50450S
FSB50450US		FSSP50CH60S/FSB50450S
FSB50825US		FSSP50CH60S/FSB50450S